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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	72 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c57c-04e-so

4.4 RC Oscillator

For timing insensitive applications, the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (R_{EXT}) and capacitor (C_{EXT}) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low C_{EXT} values. The user also needs to take into account variation due to tolerance of external R and C components used.

Figure 4-5 shows how the R/C combination is connected to the PIC16C5X. For R_{EXT} values below 2.2 k Ω , the oscillator operation may become unstable, or stop completely. For very high R_{EXT} values (e.g., 1 M Ω) the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend keeping R_{EXT} between 3 k Ω and 100 k Ω .

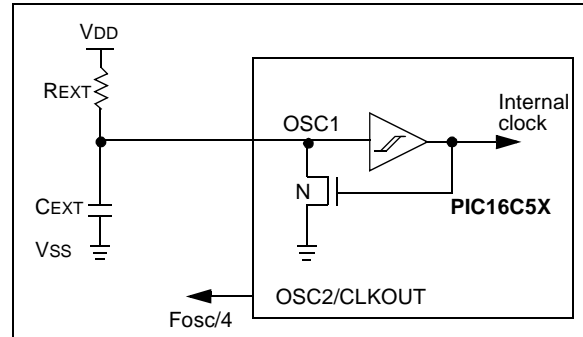
Although the oscillator will operate with no external capacitor ($C_{EXT} = 0$ pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

The Electrical Specifications sections show RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

Also, see the Electrical Specifications sections for variation of oscillator frequency due to V_{DD} for given R_{EXT}/C_{EXT} values as well as frequency variation due to operating temperature for given R, C, and V_{DD} values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic.

FIGURE 4-5: RC OSCILLATOR MODE



Note: If you change from this device to another device, please verify oscillator characteristics in your application.

PIC16C5X

FIGURE 8-3: TIMER0 TIMING: INTERNAL CLOCK/NO PRESCALER

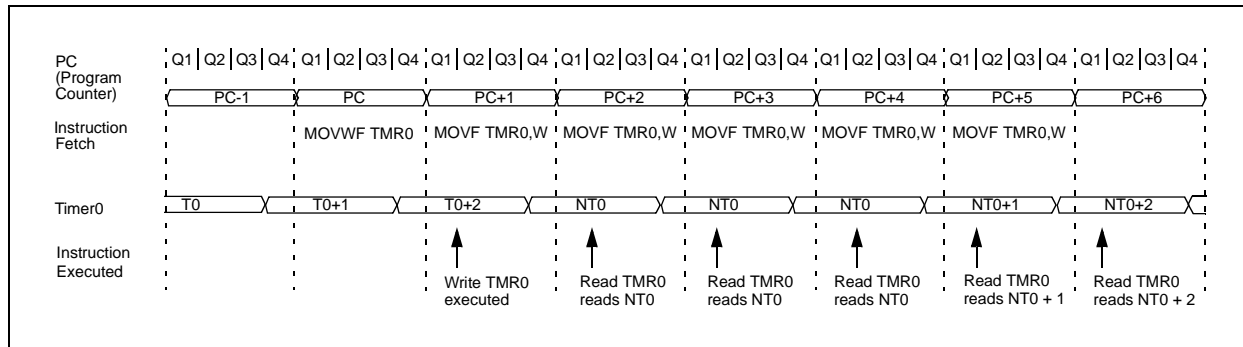


FIGURE 8-4: TIMER0 TIMING: INTERNAL CLOCK/PRESCALER 1:2

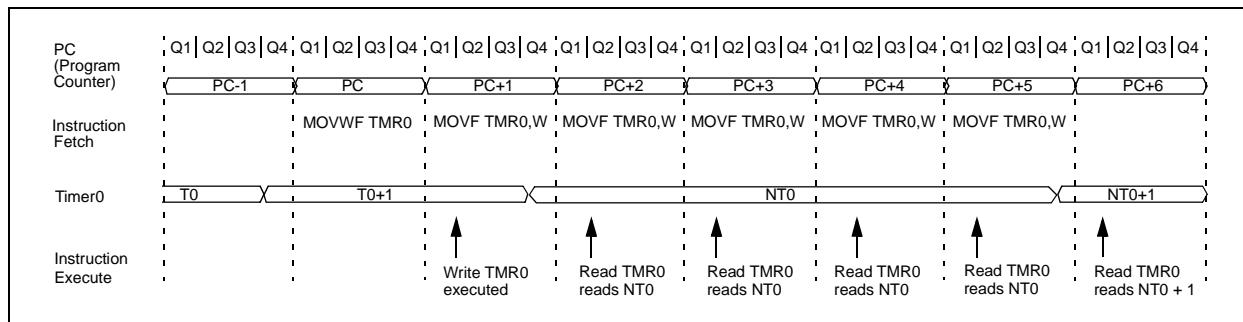


TABLE 8-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on MCLR and WDT Reset
01h	TMR0	Timer0 - 8-bit real-time clock/counter								xxxx xxxx	uuuu uuuu
N/A	OPTION	—	—	T0CS	T0SE	PSA	PS2	PS1	PS0	--11 1111	--11 1111

Legend: x = unknown, u = unchanged, - = unimplemented. Shaded cells not used by Timer0.

ADDWF Add W and f

Syntax: [*label*] ADDWF f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

Operation: (W) + (f) → (dest)

Status Affected: C, DC, Z

Encoding:

0001	11df	ffff
------	------	------

Description: Add the contents of the W register and register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is '1' the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example: ADDWF TEMP_REG, 0

Before Instruction

W = 0x17

TEMP_REG = 0xC2

After Instruction

W = 0xD9

TEMP_REG = 0xC2

ANDWF AND W with f

Syntax: [*label*] ANDWF f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

Operation: (W) .AND. (f) → (dest)

Status Affected: Z

Encoding:

0001	01df	ffff
------	------	------

Description: The contents of the W register are AND'ed with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is '1' the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example: ANDWF TEMP_REG, 1

Before Instruction

W = 0x17

TEMP_REG = 0xC2

After Instruction

W = 0x17

TEMP_REG = 0x02

ANDLW AND literal with W

Syntax: [*label*] ANDLW k

Operands: $0 \leq k \leq 255$

Operation: (W).AND. (k) → (W)

Status Affected: Z

Encoding:

1110	kkkk	kkkk
------	------	------

Description: The contents of the W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example: ANDLW H'5F'

Before Instruction

W = 0xA3

After Instruction

W = 0x03

BCF Bit Clear f

Syntax: [*label*] BCF f,b

Operands: $0 \leq f \leq 31$
 $0 \leq b \leq 7$

Operation: $0 \rightarrow (f)$

Status Affected: None

Encoding:

0100	bbbf	ffff
------	------	------

Description: Bit 'b' in register 'f' is cleared.

Words: 1

Cycles: 1

Example: BCF FLAG_REG, 7

Before Instruction

FLAG_REG = 0xC7

After Instruction

FLAG_REG = 0x47

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12.7 Timing Diagrams and Specifications

FIGURE 12-2: EXTERNAL CLOCK TIMING - PIC16C54/55/56/57

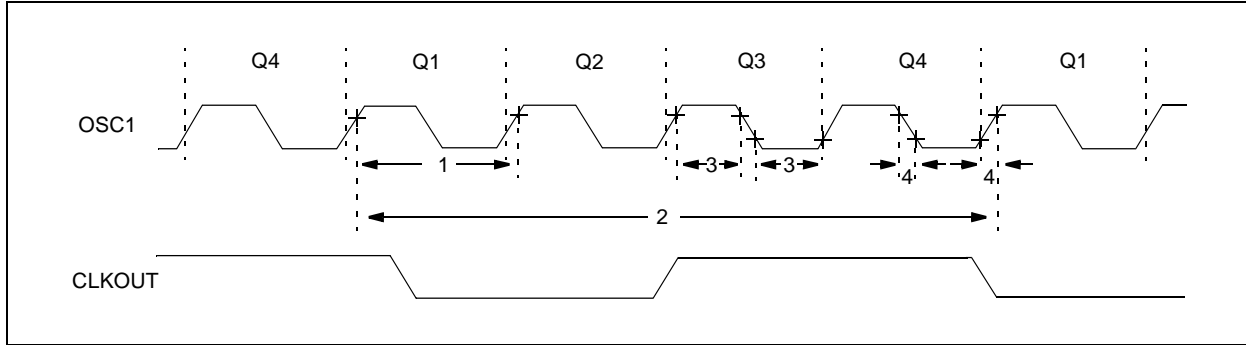


TABLE 12-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54/55/56/57

Standard Operating Conditions (unless otherwise specified)							
AC Characteristics							
Operating Temperature							
0°C ≤ TA ≤ +70°C for commercial							
-40°C ≤ TA ≤ +85°C for industrial							
-40°C ≤ TA ≤ +125°C for extended							
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
1A	FOSC	External CLKIN Frequency ⁽¹⁾	DC	—	4.0	MHz	XT osc mode
			DC	—	10	MHz	10 MHz mode
			DC	—	20	MHz	HS osc mode (Comm/Ind)
			DC	—	16	MHz	HS osc mode (Ext)
			DC	—	40	kHz	LP osc mode
		Oscillator Frequency ⁽¹⁾	DC	—	4.0	MHz	RC osc mode
			0.1	—	4.0	MHz	XT osc mode
			4.0	—	10	MHz	10 MHz mode
			4.0	—	20	MHz	HS osc mode (Comm/Ind)
			4.0	—	16	MHz	HS osc mode (Ext)
DC	—	40	kHz	LP osc mode			

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

TABLE 13-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16CR54A

Standard Operating Conditions (unless otherwise specified)							
AC Characteristics							
Operating Temperature							
0°C ≤ TA ≤ +70°C for commercial							
-40°C ≤ TA ≤ +85°C for industrial							
-40°C ≤ TA ≤ +125°C for extended							
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
1	TOSC	External CLKIN Period ⁽¹⁾	250	—	—	ns	XT osc mode
			250	—	—	ns	HS osc mode (04)
			100	—	—	ns	HS osc mode (10)
			50	—	—	ns	HS osc mode (20)
			5.0	—	—	μs	LP osc mode
		Oscillator Period ⁽¹⁾	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (04)
			100	—	250	ns	HS osc mode (10)
			50	—	250	ns	HS osc mode (20)
5.0	—	200	μs	LP osc mode			
2	Tcy	Instruction Cycle Time ⁽²⁾	—	4/Fosc	—	—	
3	TosL, TosH	Clock in (OSC1) Low or High Time	50*	—	—	ns	XT oscillator
			20*	—	—	ns	HS oscillator
			2.0*	—	—	μs	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	—	25*	ns	XT oscillator
			—	—	25*	ns	HS oscillator
			—	—	50*	ns	LP oscillator

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

PIC16C5X

FIGURE 13-5: TIMER0 CLOCK TIMINGS - PIC16CR54A

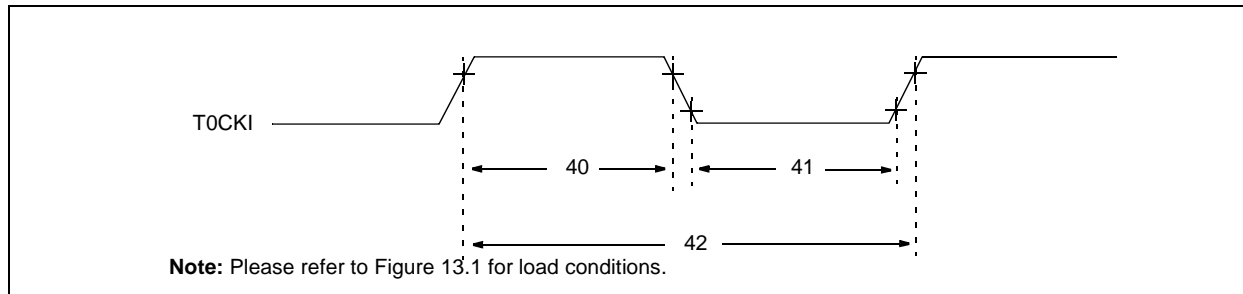


TABLE 13-4: TIMER0 CLOCK REQUIREMENTS - PIC16CR54A

AC Characteristics		Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width					
		- No Prescaler	0.5 Tcy + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width					
		- No Prescaler	0.5 Tcy + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period	20 or $\frac{Tcy + 40*}{N}$	—	—	ns	Whichever is greater. N = Prescale Value (1, 2, 4, ..., 256)

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 14-13: MAXIMUM IDD VS. FREQUENCY (EXTERNAL CLOCK, -40°C TO +85°C)

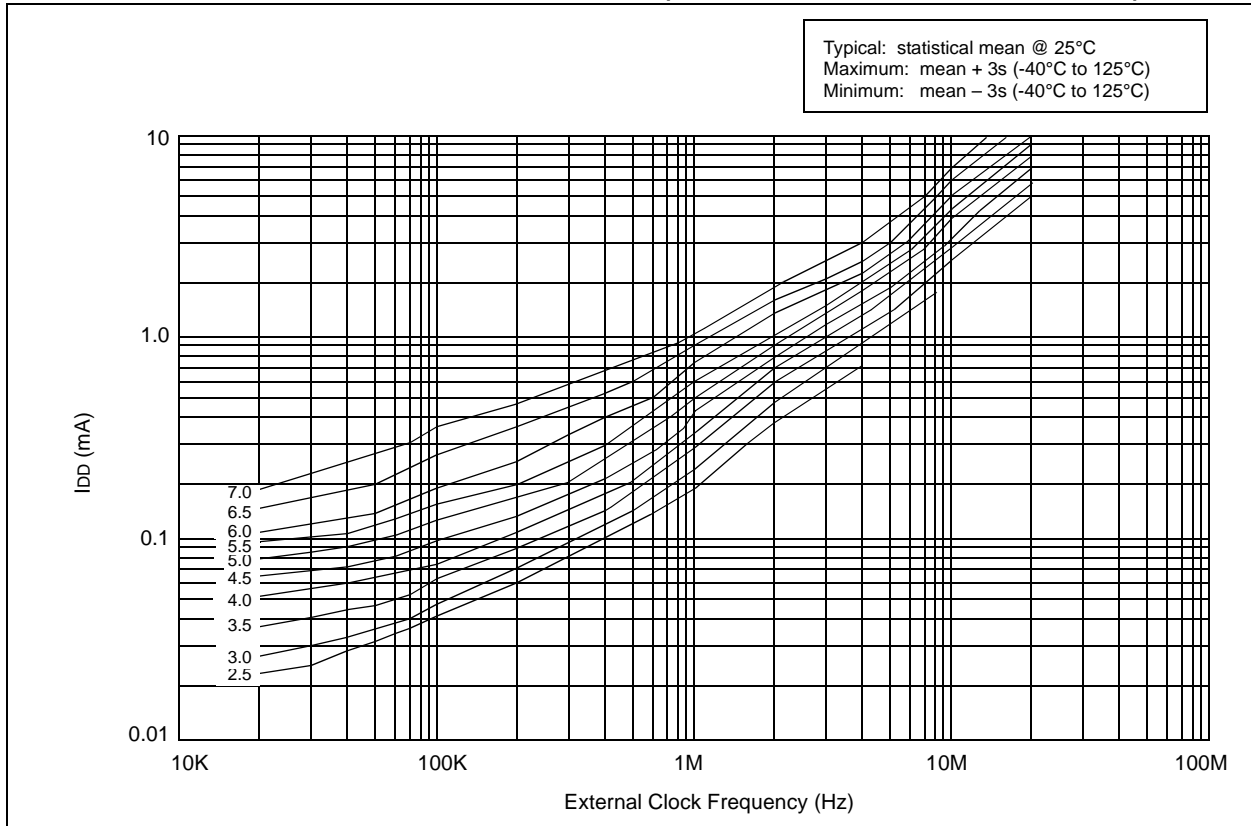


FIGURE 14-14: MAXIMUM IDD vs. FREQUENCY (EXTERNAL CLOCK -55°C TO +125°C)

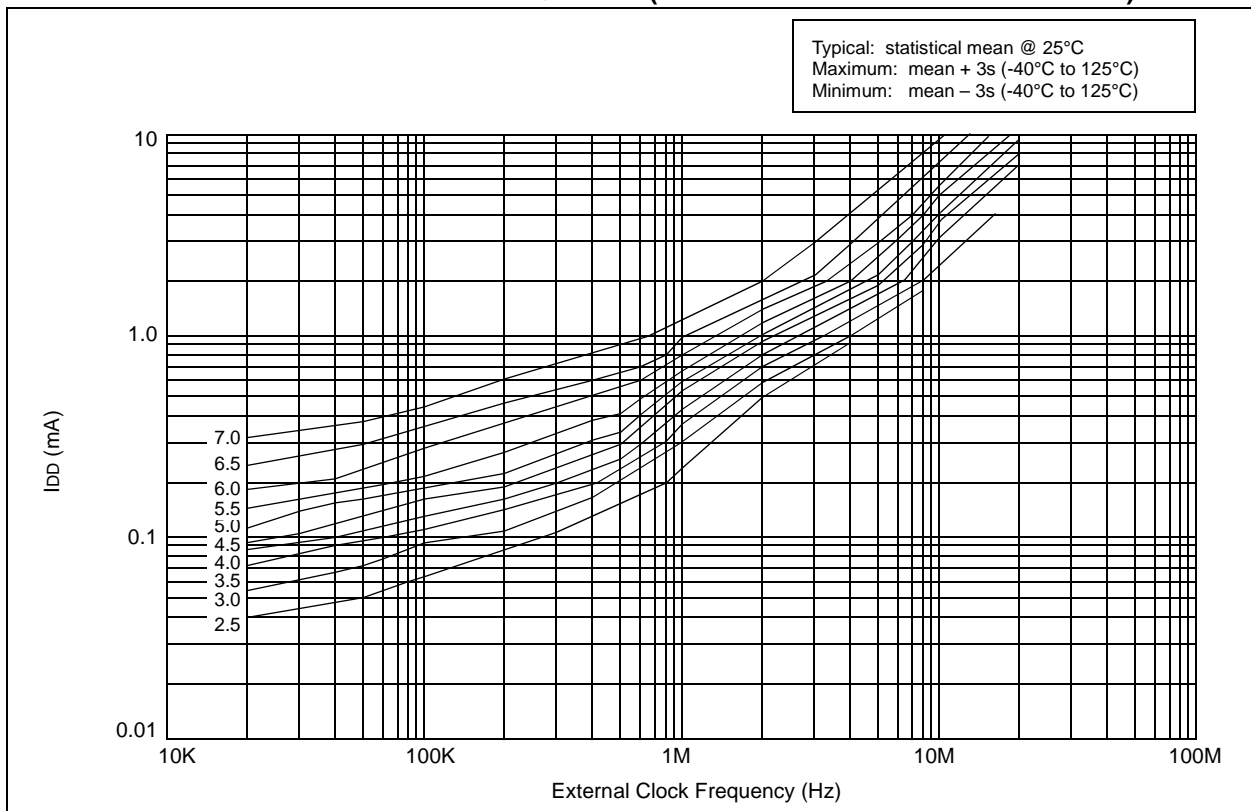


FIGURE 14-21: PORTA, B AND C I_{OL} vs. V_{OL}, V_{DD} = 3 V

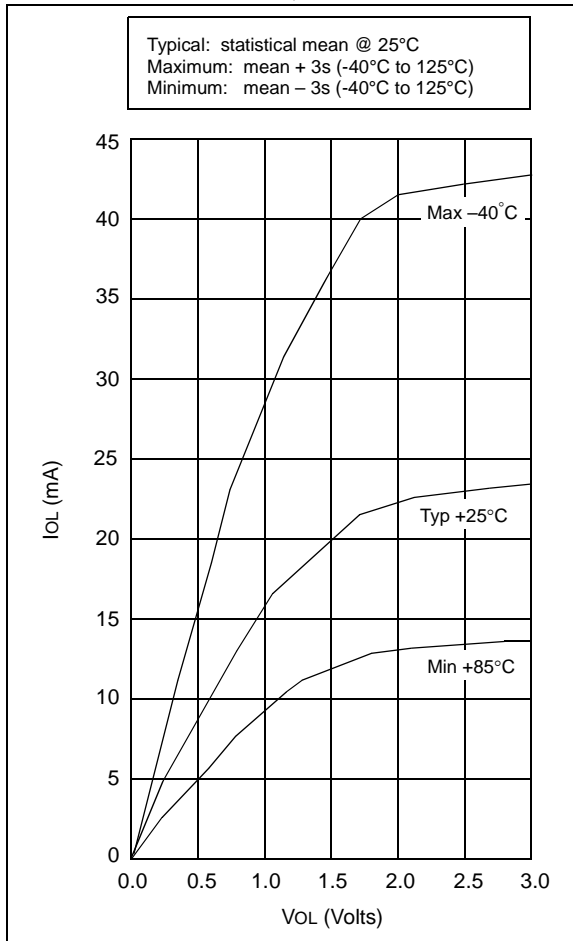
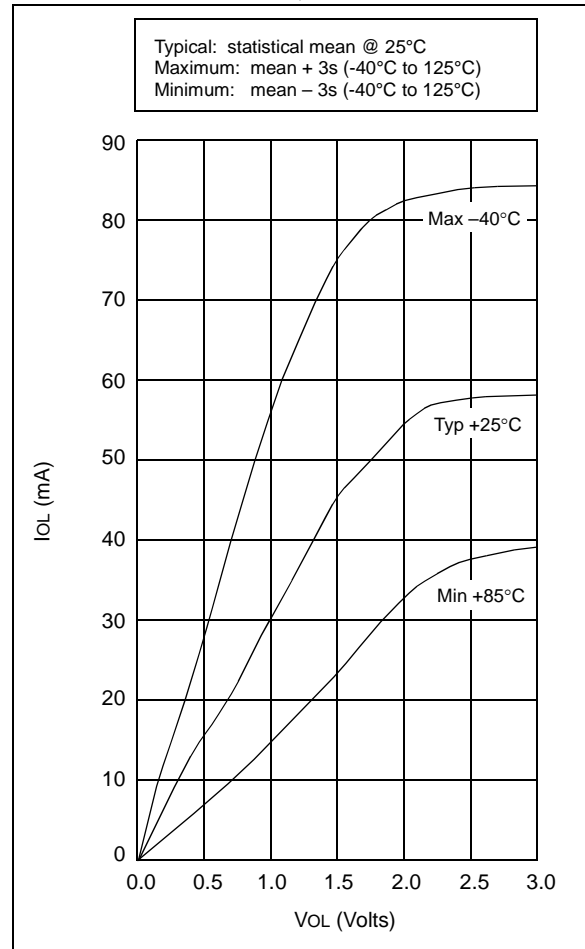


FIGURE 14-22: PORTA, B AND C I_{OL} vs. V_{OL}, V_{DD} = 5 V



PIC16C5X

TABLE 14-2: INPUT CAPACITANCE FOR PIC16C54/56

Pin	Typical Capacitance (pF)	
	18L PDIP	18L SOIC
RA port	5.0	4.3
RB port	5.0	4.3
$\overline{\text{MCLR}}$	17.0	17.0
OSC1	4.0	3.5
OSC2/CLKOUT	4.3	3.5
T0CKI	3.2	2.8

All capacitance values are typical at 25°C. A part-to-part variation of $\pm 25\%$ (three standard deviations) should be taken into account.

TABLE 14-3: INPUT CAPACITANCE FOR PIC16C55/57

Pin	Typical Capacitance (pF)	
	28L PDIP (600 mil)	28L SOIC
RA port	5.2	4.8
RB port	5.6	4.7
RC port	5.0	4.1
$\overline{\text{MCLR}}$	17.0	17.0
OSC1	6.6	3.5
OSC2/CLKOUT	4.6	3.5
T0CKI	4.5	3.5

All capacitance values are typical at 25°C. A part-to-part variation of $\pm 25\%$ (three standard deviations) should be taken into account.

15.0 ELECTRICAL CHARACTERISTICS - PIC16C54A

Absolute Maximum Ratings^(†)

Ambient temperature under bias	-55°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on VDD with respect to VSS	0 to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS.....	0 to +14V
Voltage on all other pins with respect to VSS	-0.6V to (VDD + 0.6V)
Total power dissipation ⁽¹⁾	800 mW
Max. current out of VSS pin	150 mA
Max. current into VDD pin	100 mA
Max. current into an input pin (T0CKI only)	±500 μ A
Input clamp current, I _{IK} (V _I < 0 or V _I > VDD).....	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > VDD)	±20 mA
Max. output current sunk by any I/O pin	25 mA
Max. output current sourced by any I/O pin	20 mA
Max. output current sourced by a single I/O port (PORTA or B)	50 mA
Max. output current sunk by a single I/O port (PORTA or B)	50 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

† NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

PIC16C5X

NOTES:

16.0 DEVICE CHARACTERIZATION - PIC16C54A

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

“Typical” represents the mean of the distribution at 25°C. “Maximum” or “minimum” represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 16-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE



TABLE 16-1: RC OSCILLATOR FREQUENCIES

CEXT	REXT	Average Fosc @ 5 V, 25°C	
		Frequency	Percentage Variation
20 pF	3.3K	5 MHz	± 27%
	5K	3.8 MHz	± 21%
	10K	2.2 MHz	± 21%
	100K	262 kHz	± 31%
100 pF	3.3K	1.6 MHz	± 13%
	5K	1.2 MHz	± 13%
	10K	684 kHz	± 18%
	100K	71 kHz	± 25%
300 pF	3.3K	660 kHz	± 10%
	5.0K	484 kHz	± 14%
	10K	267 kHz	± 15%
	100K	29 kHz	± 19%

The frequencies are measured on DIP packages.

The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ±3 standard deviation from average value for VDD = 5V.

PIC16C5X

FIGURE 16-9: V_{IH} , V_{IL} OF \overline{MCLR} , $T0CKI$ AND $OSC1$ (IN RC MODE) vs. V_{DD}

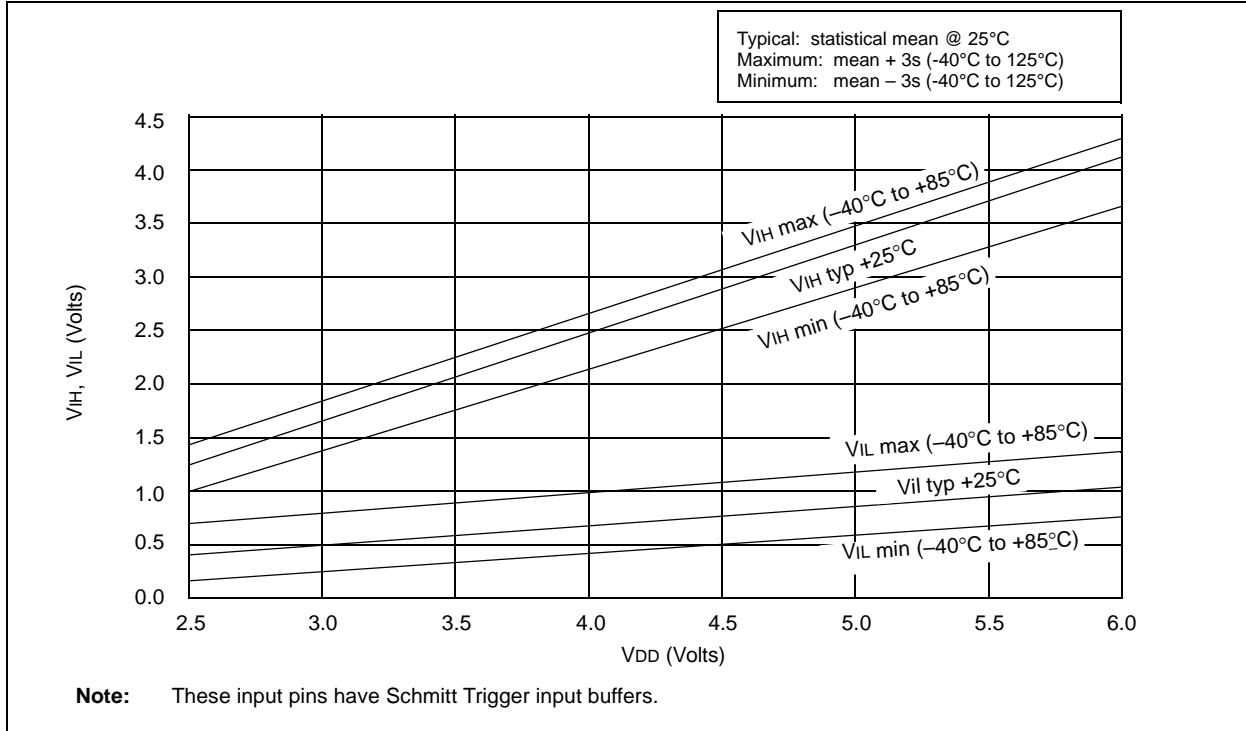


FIGURE 16-18: TRANSCONDUCTANCE (gm) OF LP OSCILLATOR vs. VDD



FIGURE 16-19: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



17.1 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial)
PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial)
PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial)
PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X PIC16LCR5X (Commercial, Industrial)		Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial					
PIC16C5X PIC16CR5X (Commercial, Industrial)		Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial					
Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
D010	IDD	Supply Current^(2,3)					
		PIC16LC5X	—	0.5	2.4	mA	FOSC = 4.0 MHz, VDD = 5.5V, XT and RC modes
			—	11	27	μA	
D010A		PIC16C5X	—	1.8	2.4	mA	FOSC = 4 MHz, VDD = 5.5V, XT and RC modes
			—	2.6	3.6*	mA	
			—	4.5	16	mA	FOSC = 10 MHz, VDD = 3.0V, HS mode FOSC = 20 MHz, VDD = 5.5V, HS mode FOSC = 32 kHz, VDD = 3.0V, LP mode, Commercial
			—	14	32	μA	
			—	17	40	μA	

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

PIC16C5X

17.1 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial) PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial) PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial) PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X PIC16LCR5X (Commercial, Industrial)		Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial					
PIC16C5X PIC16CR5X (Commercial, Industrial)		Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial					
Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
D020	IPD	Power-down Current ⁽²⁾					
		PIC16LC5X	—	0.25	2	μA	VDD = 2.5V, WDT disabled, Commercial
			—	0.25	3	μA	VDD = 2.5V, WDT disabled, Industrial
			—	1	5	μA	VDD = 2.5V, WDT enabled, Commercial
—	1.25		8	μA	VDD = 2.5V, WDT enabled, Industrial		
D020A	IPD	PIC16C5X	—	0.25	4.0	μA	VDD = 3.0V, WDT disabled, Commercial
			—	0.25	5.0	μA	VDD = 3.0V, WDT disabled, Industrial
			—	1.8	7.0*	μA	VDD = 5.5V, WDT disabled, Commercial
			—	2.0	8.0*	μA	VDD = 5.5V, WDT disabled, Industrial
			—	4	12*	μA	VDD = 3.0V, WDT enabled, Commercial
			—	4	14*	μA	VDD = 3.0V, WDT enabled, Industrial
			—	9.8	27*	μA	VDD = 5.5V, WDT enabled, Commercial
			—	12	30*	μA	VDD = 5.5V, WDT enabled, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

Note 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

Note 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

PIC16C5X

FIGURE 19-5: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C5X-40



TABLE 19-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C5X-40

Standard Operating Conditions (unless otherwise specified)							
AC Characteristics							
Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ (commercial)							
Operating Voltage V_{DD} range is described in Section 19.1.							
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
30	T_{mCL}	MCLR Pulse Width (low)	1000*	—	—	ns	$V_{DD} = 5.0\text{V}$
31	T_{wdt}	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	$V_{DD} = 5.0\text{V}$ (Comm)
32	T_{DRT}	Device Reset Timer Period	9.0*	18*	30*	ms	$V_{DD} = 5.0\text{V}$ (Comm)
34	T_{ioZ}	I/O Hi-impedance from MCLR Low	100*	300*	1000*	ns	

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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